AG270SN100MTB

N-Channel Enhancement Mode MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
100V	2.5mΩ@10V	270A
	3.1mΩ@6V	

Feature

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

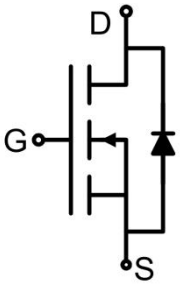
Application

- Load switch
- Battery management
- Solar

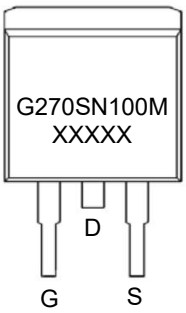
Package

TO-263AB

Circuit diagram



Marking



Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current (T_C=25℃)	I_D	270	A
Continuous Drain Current (T_C=100℃)	I_D(100℃)	190	A
Pulsed Drain Current[1)]	I_{DM}	1080	A
Single Pulse Avalanche Energy[2)]	E_{AS}	1440	mJ
Power Dissipation[3)] (T_C=25℃)	P_D	300	W
Thermal Resistance Junction to Case	$R_{\theta JC}$	0.5	℃/W
Operating Junction Temperature	T_J	-55 ~ +175	℃
Storage Temperature	T_{STG}	-55 ~ +175	℃

Electrical characteristics (T_J=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} =0V, I_D =250μA	100			V
Zero gate voltage drain current	I_{DSS}	V_{DS} =100V, V_{GS} =0V			1	μA
Gate-body leakage current	I_{GSS}	V_{DS} =0V, V_{GS} =±20V			±100	nA
Gate threshold voltage	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =250μA	2	2.6	4	V
Drain-source on-resistance	$R_{DS(on)}$	V_{GS} =10V, I_D =50A		1.9	2.5	mΩ
		V_{GS} =10V, I_D =20A		1.9	2.5	
		V_{GS} =6V, I_D =20A		2.3	3.1	
Dynamic characteristics[4)]						
Input Capacitance	C_{iss}	V_{DS} =50V, V_{GS} =0V, f =1MHz		10730		pF
Output Capacitance	C_{oss}			2125		
Reverse Transfer Capacitance	C_{rss}			33		
Total Gate Charge	Q_g	V_{DS} =50V, V_{GS} =10V, I_D =30A		166		nC
Gate-Source Charge	Q_{gs}			34		
Gate-Drain Charge	Q_{gd}			49		
Turn-on delay time	$t_{d(on)}$	V_{DS} =50V, V_{GS} =10V, I_D =30A R_G =4.5Ω		30		nS
Turn-on rise time	t_r			65		
Turn-off delay time	$t_{d(off)}$			121		
Turn-off fall time	t_f			107		
Source-Drain Diode characteristics						
Diode Forward Current	I_S				270	A
Diode Forward voltage	V_{SD}	V_{GS} =0V, I_S =50A			1.2	V
Reverse Recovery Time	T_{rr}	I_F =30A, di/dt =100A/μs		92		nS
Reverse Recovery Charge	Q_{rr}			167		nC

Notes:

1) Repetitive rating; pulse width limited by max. junction temperature.

2) T_J=25℃, V_G=10V, R_G=25Ω, L=5mH, I_{AS}=24A.

3) Pd is based on max. junction temperature, using junction-case and junction-ambient thermal resistance.

4) Guaranteed by design, not subject to production testing.

Typical Characteristics

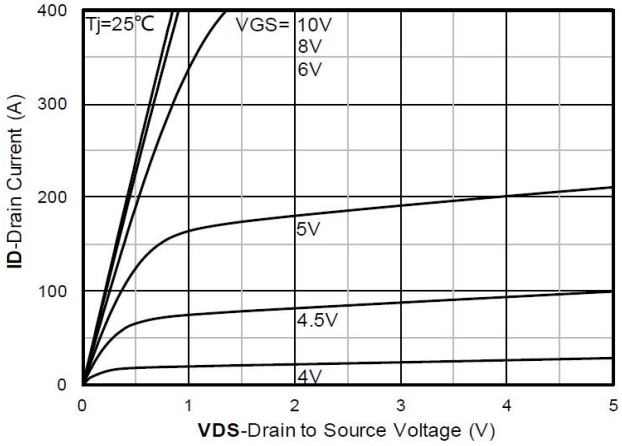


Figure 1. Output Characteristics

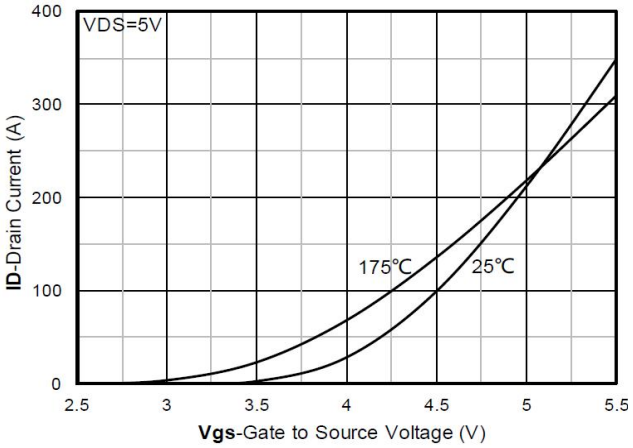


Figure 2. Transfer Characteristics

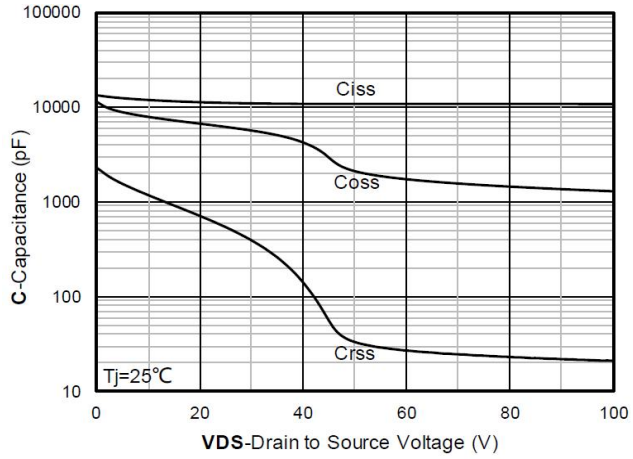


Figure 3. Capacitance Characteristics

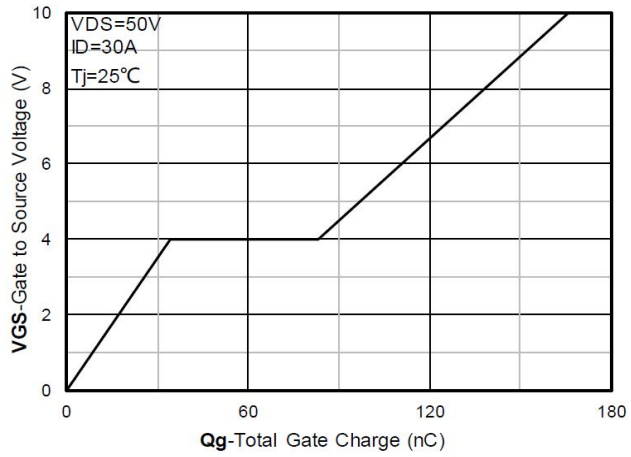


Figure 4. Gate Charge

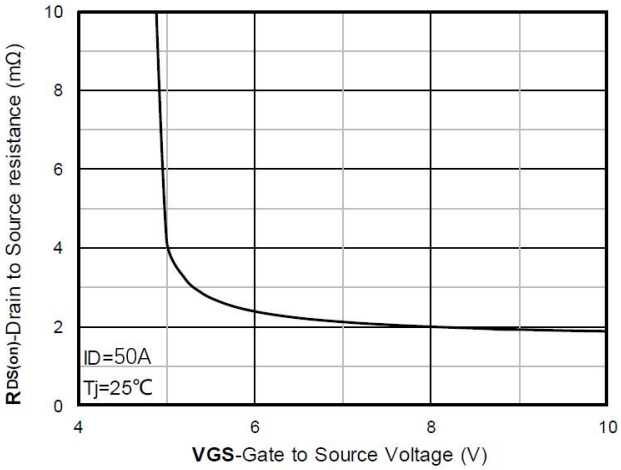


Figure 5. On-Resistance vs Gate to Source Voltage

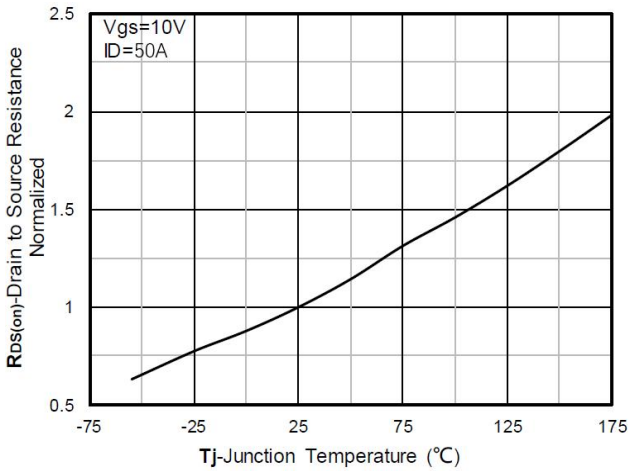


Figure 6. Normalized On-Resistance

Typical Characteristics

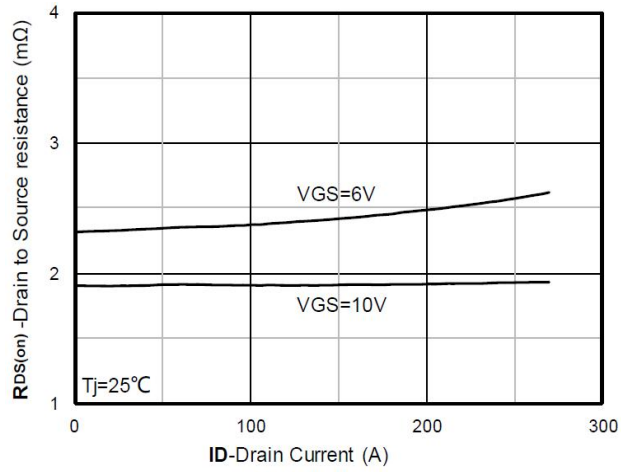


Figure 7. $R_{DS(on)}$ VS Drain Current

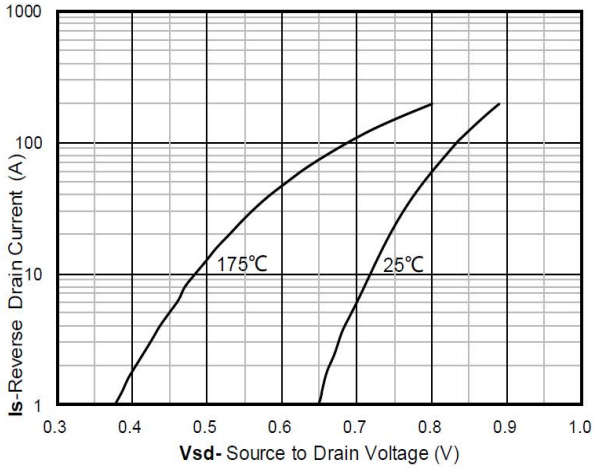


Figure 8. Forward characteristics of reverse diode

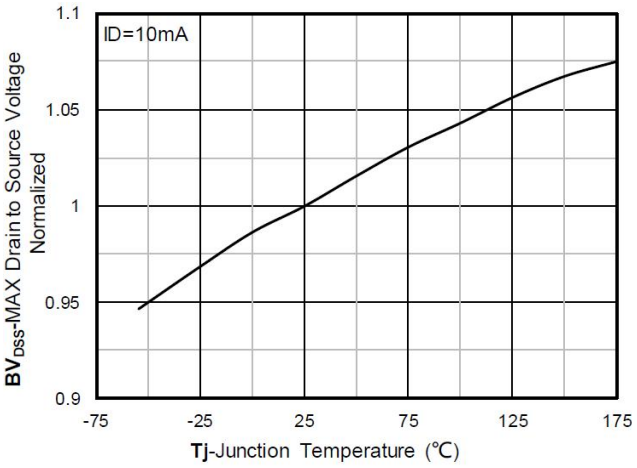


Figure 9. Normalized breakdown voltage

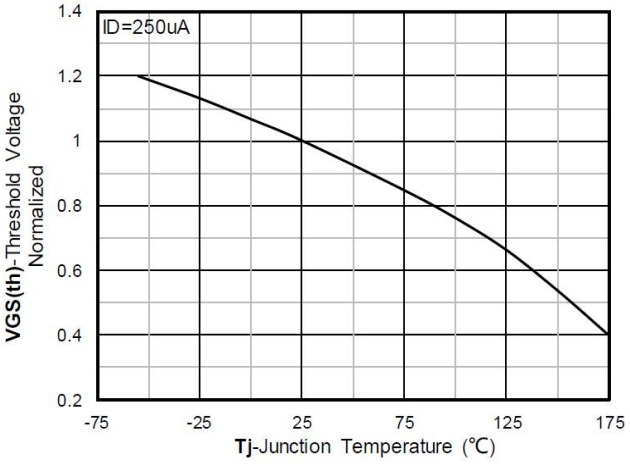


Figure 10. Normalized Threshold voltage

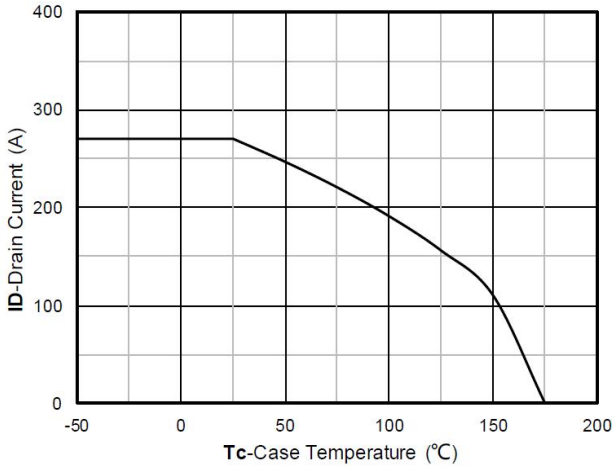


Figure 11. Current dissipation

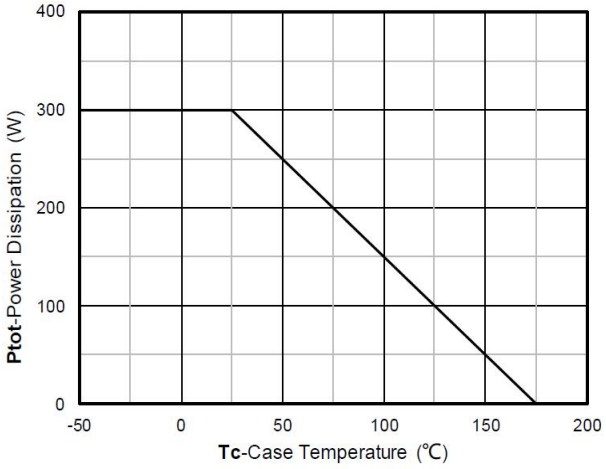


Figure 12. Power dissipation

Typical Characteristics

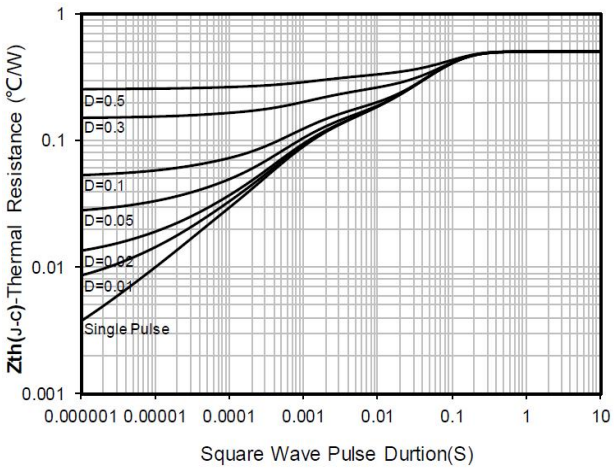


Figure 13. Maximum Transient Thermal Impedance

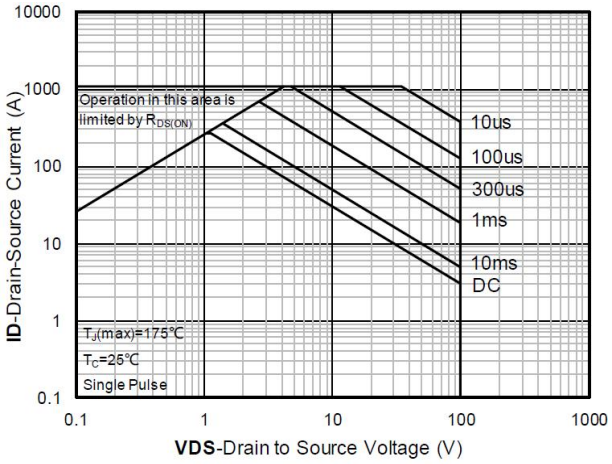
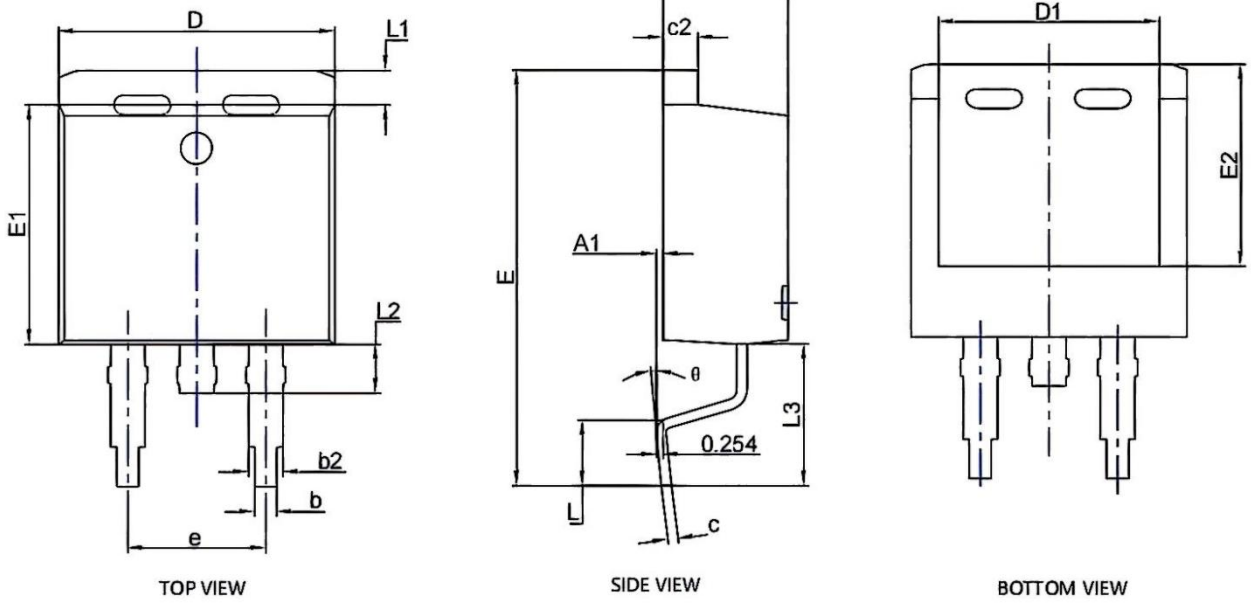


Figure 14. Safe Operation Area

TO-263AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A1	0.000	0.254	0.000	0.010
A2	4.064	4.826	0.160	0.190
b	0.508	0.991	0.020	0.039
b2	1.143	1.778	0.045	0.070
c	0.381	0.737	0.015	0.029
c2	1.143	1.651	0.045	0.065
D	9.652	10.668	0.380	0.420
D1	6.223	-	0.245	-
E	14.605	15.875	0.575	0.625
E1	8.382	9.652	0.330	0.380
E2	6.858	-	0.270	-
e	5.080 BSC.		0.200 BSC.	
L	1.778	2.794	0.070	0.110
L1	-	1.676	-	0.066
L2	-	1.778	-	0.070
L3	4.780	5.280	0.188	0.208
θ	0°	8°	0°	8°